IN THE CLAIMS:

1. (Original) A thermoconductive addition-curable liquid silicone rubber composition having a thermal conductivity of at least 0.3 W/(m·K) after curing which comprises

(A) 100 parts by weight of liquid diorganopolysiloxane that has a viscosity of 100 to 100,000 mPa·s and contains at least two silicon-bonded alkenyl groups in each molecule,

(B) 50 to 600 parts by weight of alumina micropowder that has an average particle size of 0.1 to 50 μm,

(C) 20 to 100 parts by weight of iron oxide micropowder that has an average particle size of 0.01 to 0.5 μm,

(D) 0.1 to 2.0 parts by weight of cerium oxide micropowder, cerium hydroxide micropowder, or cerium-containing heteroorganosiloxane,

(E) organopolysiloxane that contains at least two silicon-bonded hydrogen atoms in each molecule, wherein the component (E) content provides from 0.3 to 5 moles silicon-bonded hydrogen in component (E) per 1 mole silicon-bonded alkenyl in component (A), and

(F) platinum catalyst in a catalytic quantity.

2. (Original) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 1 characterized in that the particle shape of the alumina micropowder (B) is spherical or irregular.

3. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with ~~any preceding~~ claim 1 characterized in that the surface of the alumina micropowder (B) has been treated with a surface treatment agent.

4. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 3 characterized in that the surface treatment agent is an organoalkoxysilane, a tetraalkoxysilane, or a partial hydrolysis and/or condensation product of tetraalkoxysilane.

5. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with ~~any preceding~~ claim 1 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).

6. (Currently Amended) A thermoconductive addition-curable liquid silicone rubber composition in accordance with ~~any preceding~~ claim 1 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

7. (Currently Amended) Use of a thermoconductive addition-curable liquid silicone rubber composition according to ~~any preceding~~ claim 1 in a fixing roll for electrophotographic copiers, electronic printers [[and]] or facsimile machines.

8. (Currently Amended) Use in accordance with claim 7 wherein [[said]] the fixing roll is a coated fixing roll comprising a fluororesin layer or a fluororubber layer disposed on the peripheral surface of a roll shaft, with [[said]] the thermoconductive addition-curable liquid silicone rubber composition interposed between the fluororesin layer and the roll shaft.

9. (Currently Amended) A coated fixing roll comprising a fluororesin layer or a fluororubber layer disposed on the peripheral surface of a roll shaft, and a silicone rubber layer interposed between the fluororesin layer or the fluororubber layer and the roll shaft, the [[which]] silicone rubber layer being the cured product of the thermoconductive addition-curable liquid silicone rubber composition ~~in accordance with any one of claims 1 to 6~~ of claim 1.

Please add the following new claims.

10. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 2 characterized in that the surface of the alumina micropowder (B) has been treated with a surface treatment agent.

11. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 10 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).

12. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 2 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).

13. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 3 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).

14. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 4 characterized in that component (C) is in the form of a paste comprising a microdispersion of component (C) in a portion of component (A).

15. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 2 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

16. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 3 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

17. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 4 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

18. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 5 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

19. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 10 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).

20. (New) A thermoconductive addition-curable liquid silicone rubber composition in accordance with claim 11 characterized in that component (D) is in the form of a paste comprising a microdispersion of component (D) in a portion of component (A).